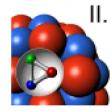


The PASTA chip for the silicon micro strip sensor of the PANDA **MVD**

Alberto Riccardi¹

Kai-Thomas Brinkmann¹, Valentino Di Pietro¹, Tommaso Quagli¹, James Ritman², Angelo Rivetti³, Manuel Rolo³, Robert Schnell¹, Tobias Stockmanns², André Zambanini², and Hans-Georg Zaunick¹

- 1) II. Physikalisches Institut Justus-Liebig-Universität Giessen
- 2) Forschungszentrum Jülich
- 3) INFN Sezione di Torino



II. Physikalisches Institut

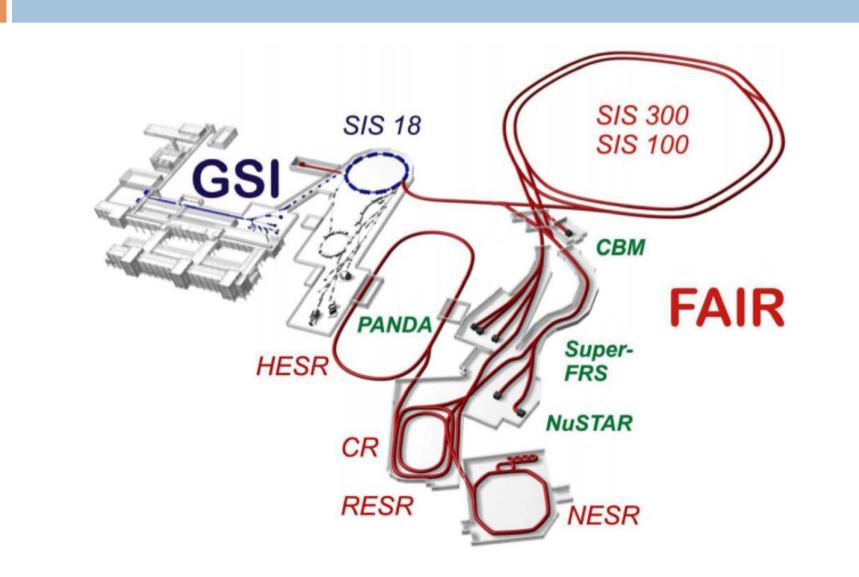
DPG Spring Meeting 2016



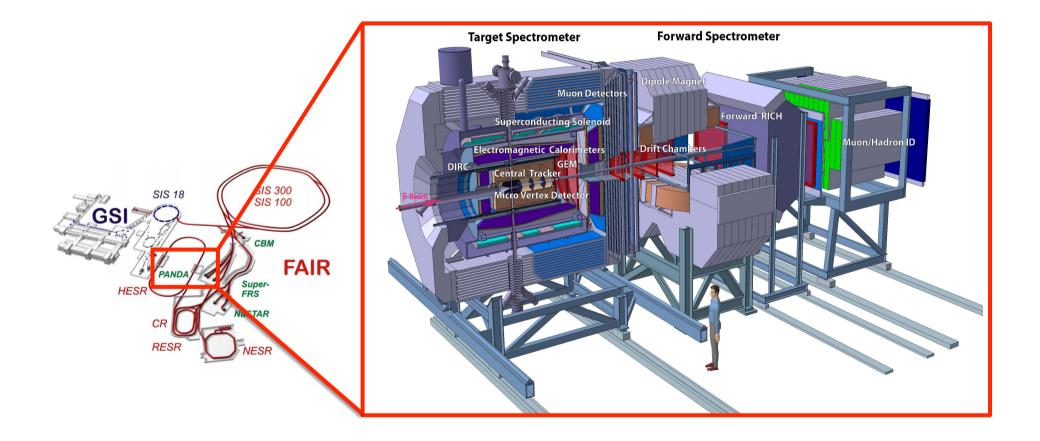
Contents

- 1. Context
- 2. ASIC design
- 3. Current status
- 4. Outlook

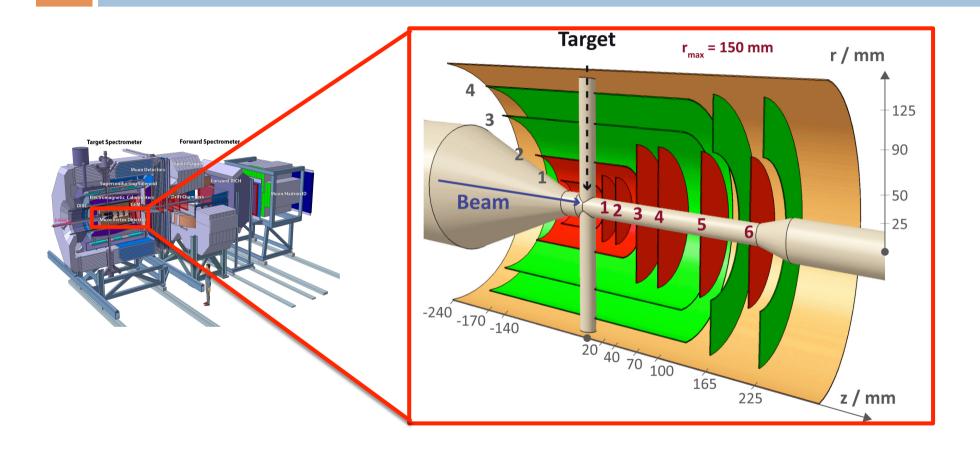




PANDA

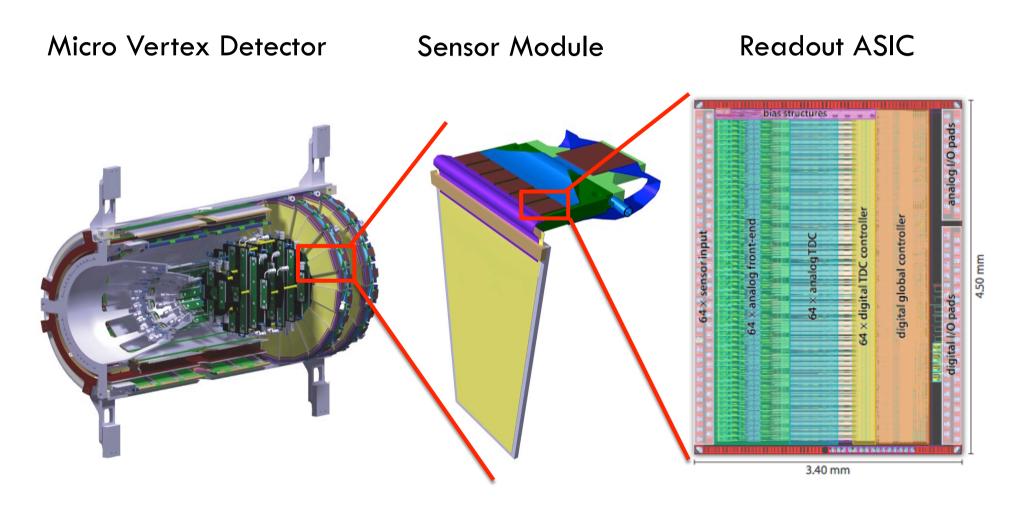


MicroVertex Detector



Red zone covered by pixels and green one by strips

PAnda STrip Asic (PASTA)

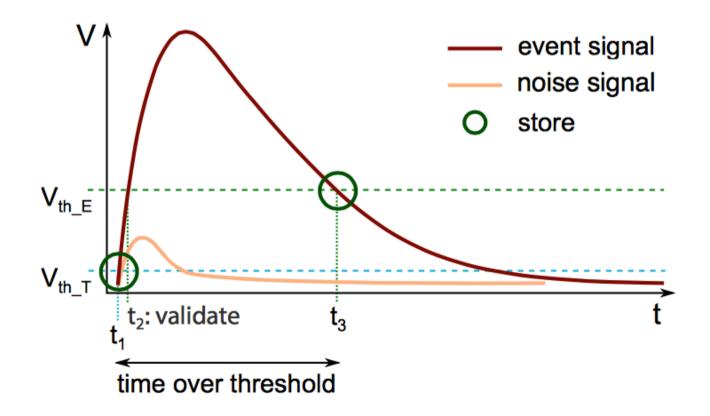


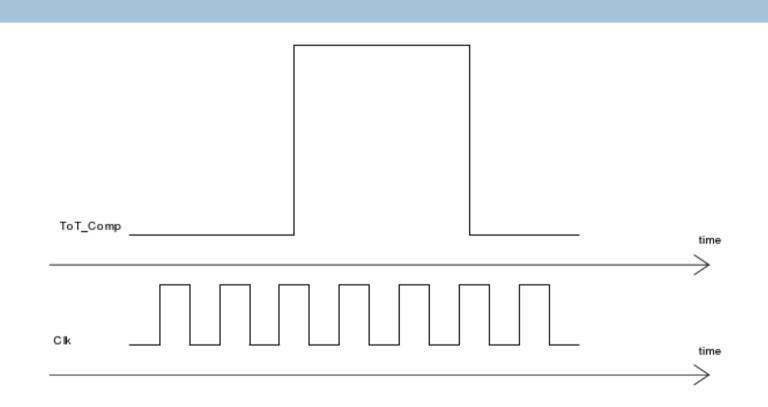
PASTA Features

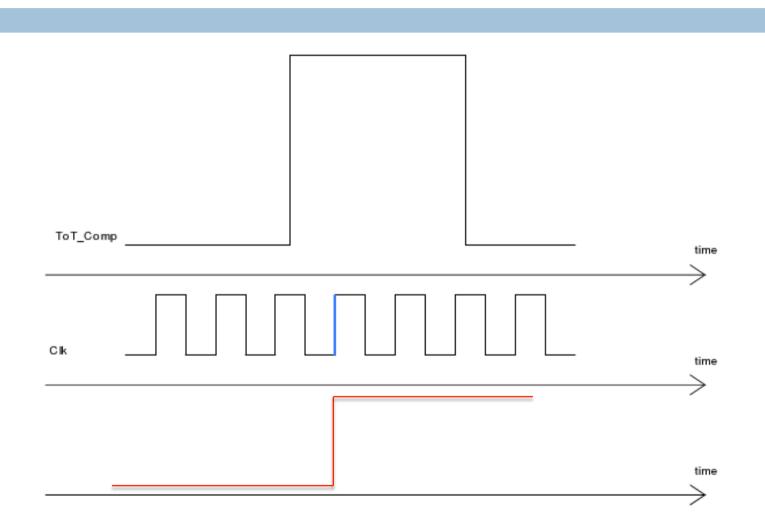
- 64 Channels
- \Box 63 μ m input pitch
- 100 kHz Rate/channel
- □ Less then 4 mW per channel
- □ Triggerless
- Radiation tolerance 100 kGy

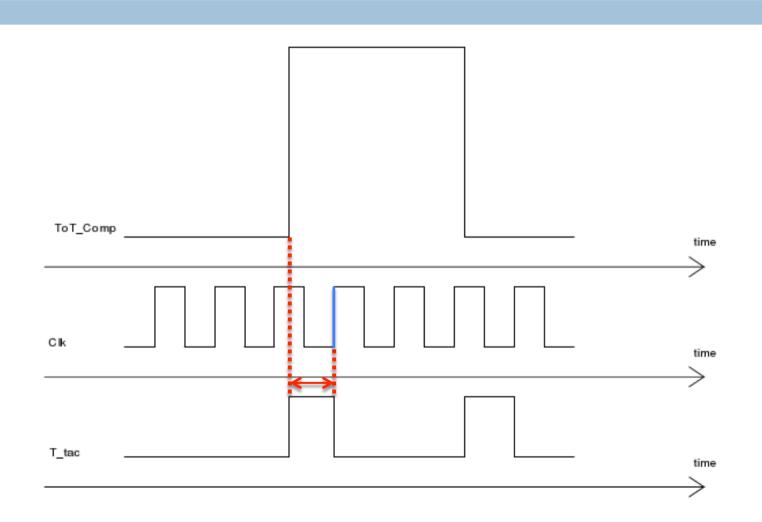
Measurement Concept

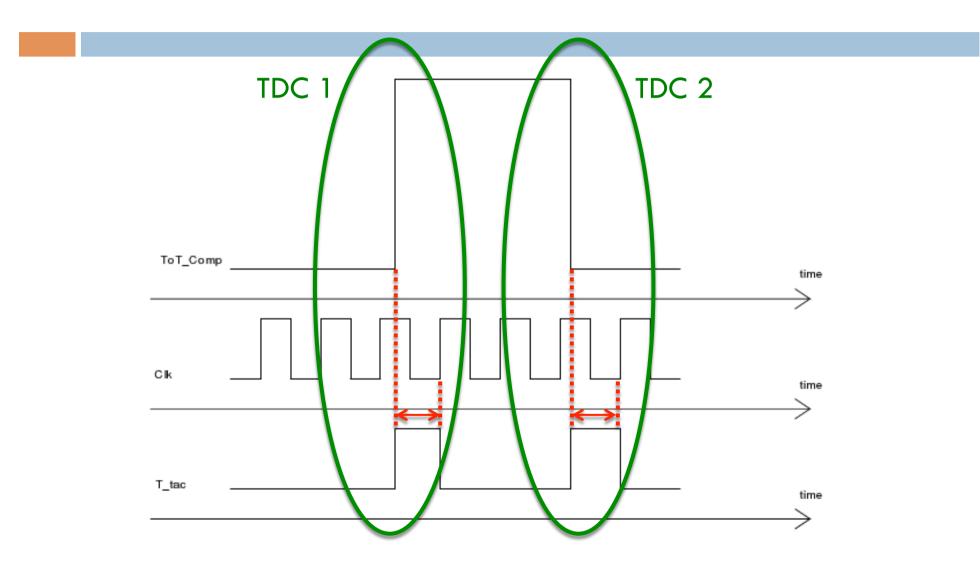
- Low threshold: better time stamp resolution
- High threshold: better jitter performance



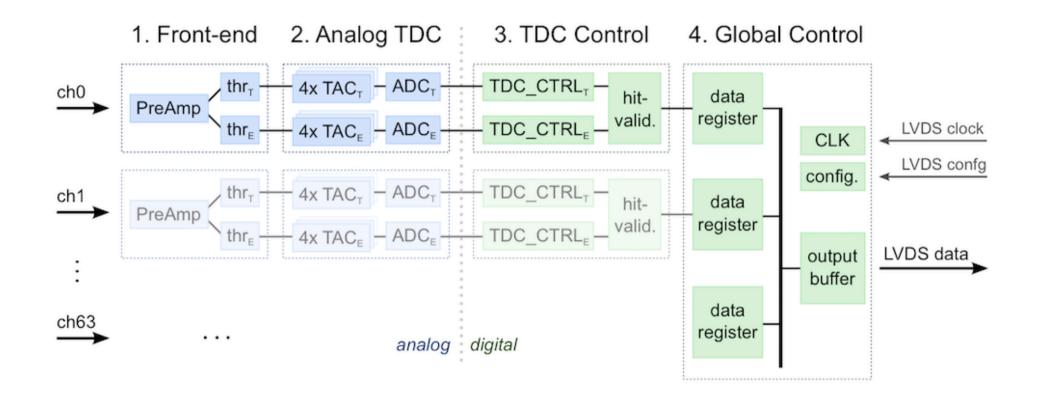


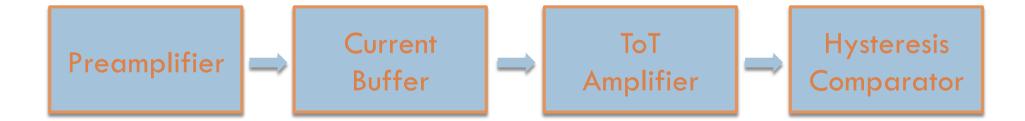




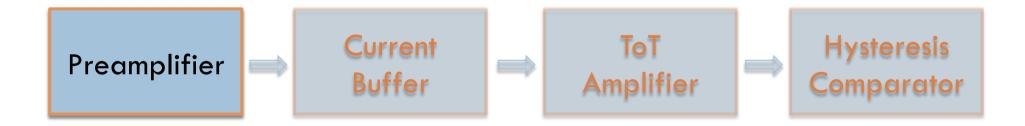


PASTA Architecture

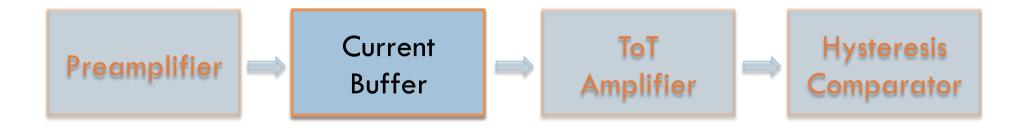




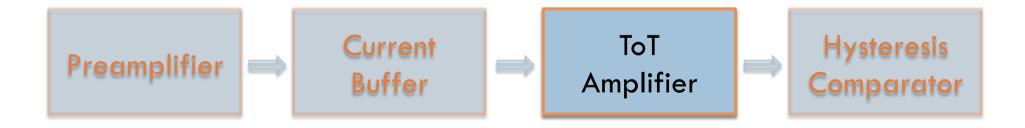
- First preamplification
- Two input polarities, same output polarity



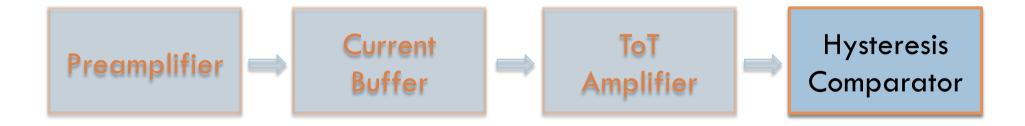
- Current amplification
- Impedance adapter



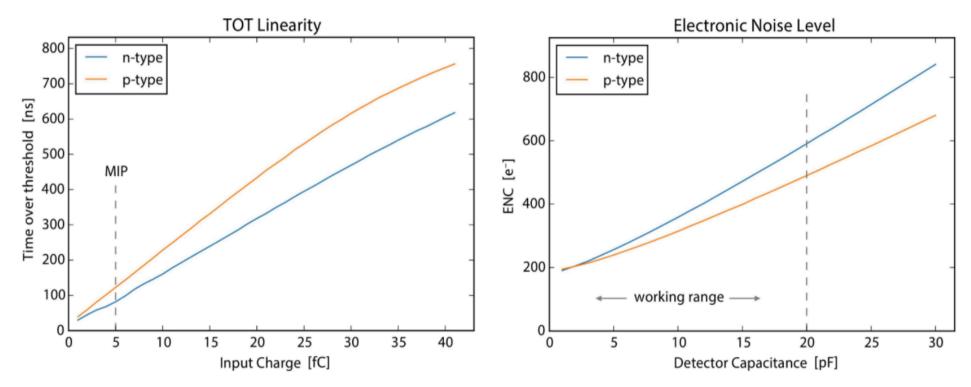
- Last amplification
- Constant current discharge of feedback capacitance



- Low noise sensitivity
- Two for each channel : energy and time branches

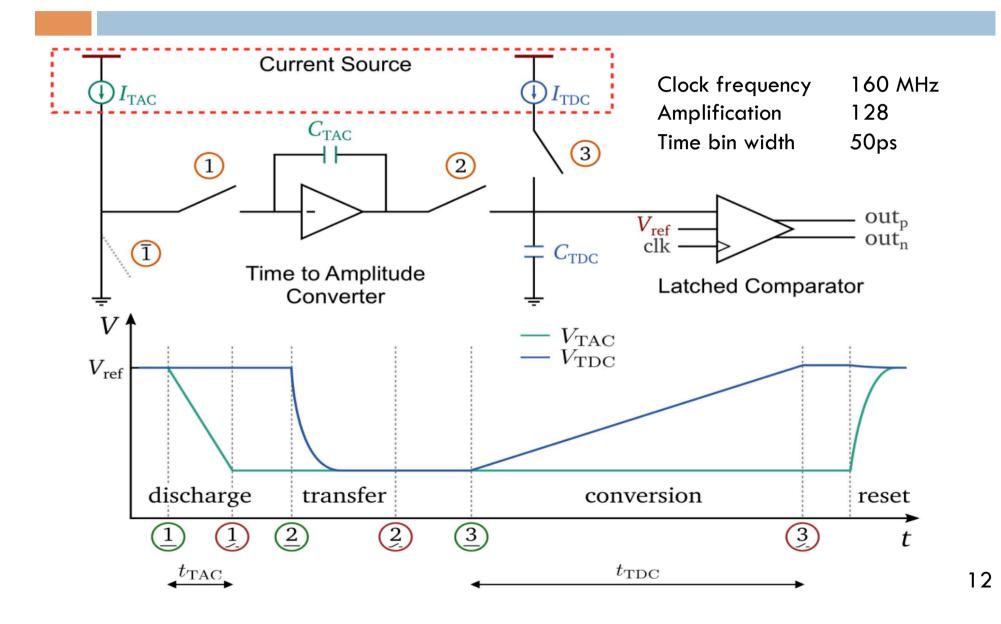


Front-End Simulations



ToT linearity in the input charge range of 1fC to 40 fC with a capacitance of 25 pF Electronic noise considering an input capacitance in the range 1pF to 30 pF with an input charge of 4fC

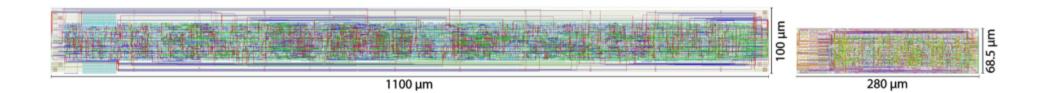
Analog TDC Performance



Digital Controllers

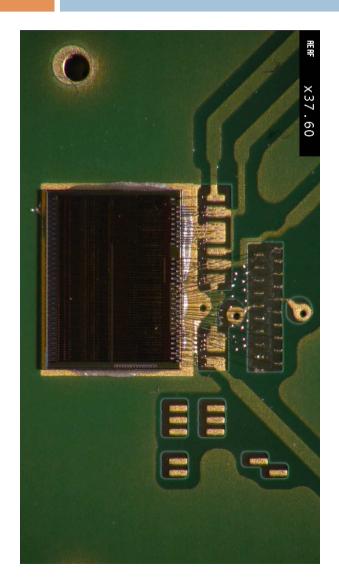
Optimization of the TDC Controller

- Size reduced by 80%
- Overall power consumption halved
- Radiation-hard logic implemented



- Single Event Upset protection
 - 1 bit : TripleModular redundancy
 - n bits : Hamming encoding

Current Status



- Chip bonded to the power board
- Power supplies tested
- Readout system under test

Outlook

□ Board in production

□ First tests scheduled

Beam test with sensor planned in the middle of the year









Alberto Riccardi

Alberto.Riccardi@exp2.physik.uni-giessen.de

Thank you for your attention

GEFÖRDERT VOM



Bundesministerium für Bildung und Forschung









II. Physikalisches Institut



